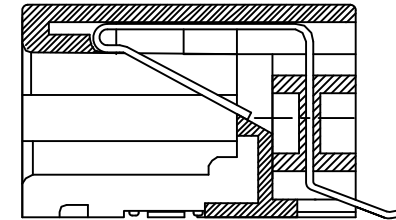
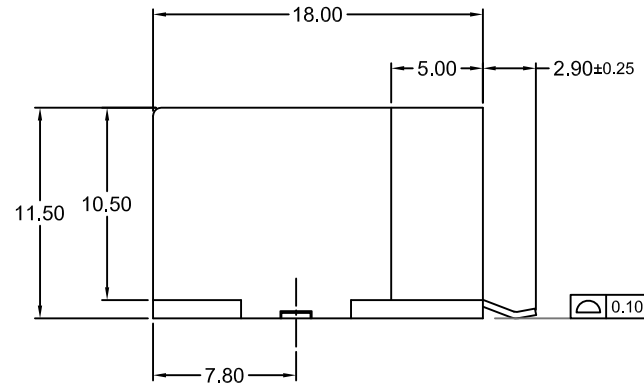
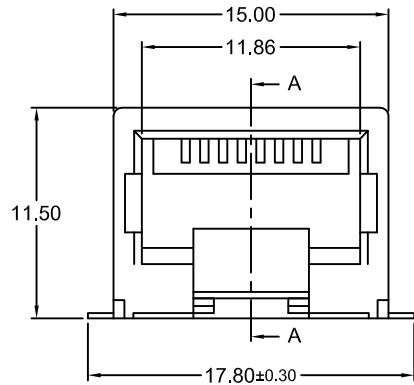
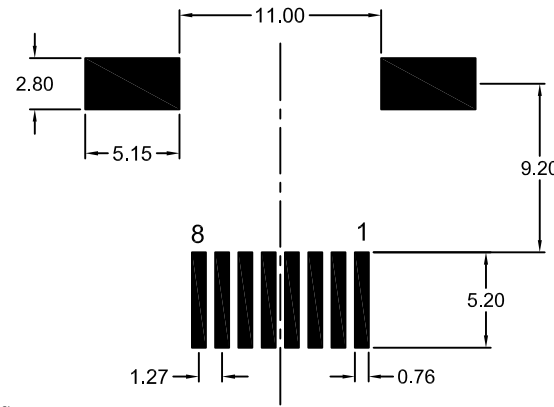
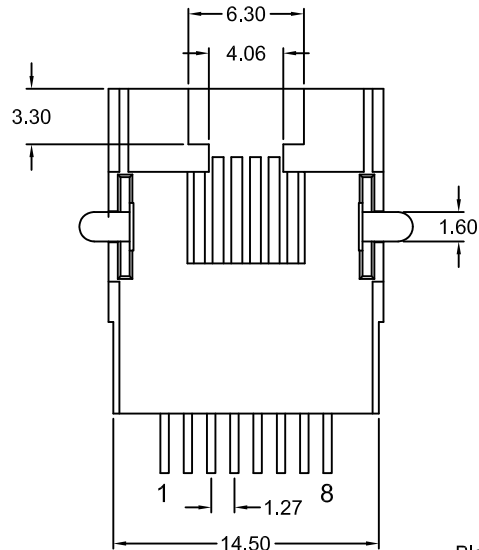


REV.	DESCRIPTION	DATE	DRAWN
A	NEW	28.06.2013	Ronny
B	dim 18,00 -> 17,80±0,30	28.11.2013	Ronny



A-A



Recommended PCB SMT Layout  
(PCB TOLERANCE ±0.05)

Blank: Tray packing  
/R = Reel packing

PART NUMBER	GOLD PLATING CONTACT AREA
MJS-108-WD3S1-56/R	6μ"
MJS-108-WD3S1-57/R	15μ"
MJS-108-WD3S1-58/R	30μ"
MJS-108-WD3S1-5H/R	50μ"

### Specifications

Current rating: 1.5A  
 Insulation resistance: 500MΩ min. / 500V DC  
 Withstanding voltage: 1000V rms 60Hz / Minute  
 Contact resistance: 40mΩ max. / 20mV DC

### Materials

Contact: Phosphor Bronze t=0.35mm  
 Plating: Au flash in solder area  
 Insulator: PA9T UL 94V-0 (Black)

Operating temperature: -40°C to +105°C  
 Processing temperature: +250°C +0/-5°C  
 for 10 seconds

Cavity confirms to FCC Rules and  
 Registration PAR68, Subparts F.



UNIT mm	GENERAL TOLERANCE		DRAWN Ronny	DATE 28.06.2013	DWG. NO.	SHEET 1/1
	X.° ±	.X ±	CHECK Hogi	DATE 28.11.2013	1711601	REV. B
	X. ±	.X ± 0.25	APPROVE Hogi	DATE 28.11.2013	Series NO.	
	XX. ±	.XX ± 0.13			MJS-108-WD3S1-5x/X	
SCALE Free	Ang. ± 0° 30'	.XXX ± 0.05				

**SMT PCB JACK SIDE ENTRY**  
 (RJ45) RJ50 <10P8C> non shielded  
 wing solder tabs